

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Eiji Mugiya</td> <td>08/31/2012</td> </tr> <tr> <td>Tetsuo Saji</td> <td>09/03/2012</td> </tr> <tr> <td>Takashi Matsuda</td> <td>08/27/2012</td> </tr> <tr> <td>Hiroshi Nakamura</td> <td>09/03/2012</td> </tr> </tbody> </table>		Name	Execution Date	Eiji Mugiya	08/31/2012	Tetsuo Saji	09/03/2012	Takashi Matsuda	08/27/2012	Hiroshi Nakamura	09/03/2012
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CORRESPONDENCE DATA											
<p>Fax Number: 2402382825 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 408-530-8033 Email: patents@cyiplaw.com Correspondent Name: Masao Yoshimura, Chen Yoshimura LLP Address Line 1: 333 W. El Camino Real Address Line 2: Suite 380 Address Line 4: Sunnyvale, CALIFORNIA 94087</p>											
ATTORNEY DOCKET NUMBER:	88249.JP12-0042-US										
NAME OF SUBMITTER:	Maiko Kuwada										
<p>Total Attachments: 2 source=JP12-0042-US_Assignment#page1.tif source=JP12-0042-US_Assignment#page2.tif</p>											

OP \$40.00 13589531

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

SUBSTRATE WITH BUILT-IN ELECTRONIC COMPONENT

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on August 20, 2012, (Application No. 13/589,531); and

WHEREAS, Taiyo Yuden Co., Ltd., a corporation of Japan, whose post office address is 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Eiji Mugiya	Assignor's Signature <i>Eiji Mugiya</i>	Date 08/31/2012
Address c/o Taiyo Yuden Co., Ltd. 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan		Citizenship Japan
Full Name of Second Assignor Tetsuo Saji	Assignor's Signature <i>佐治 哲生</i>	Date 09/03/2012
Address c/o Taiyo Yuden Co., Ltd. 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan		Citizenship Japan
Full Name of Third Assignor Takashi Matsuda	Assignor's Signature <i>Takashi Matsuda</i>	Date 08/27/2012
Address c/o Taiyo Yuden Co., Ltd. 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

ATTORNEY DOCKET NO.: 88249.JP12-0042-US

Full Name of Fourth Assignor Hiroshi Nakamura	Assignor's Signature <i>Hiroshi Nakamura</i>	Date 09/03/2012
Address c/o Taiyo Yuden Co., Ltd. 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan		Citizenship Japan